

### DESCRIPTION

The AM05N10 is available in SOT-223 packages.

VDSS	R <sub>DS(ON)</sub> @10(typ)	lo
100V	125mΩ	5A

## APPLICATION

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Motor control

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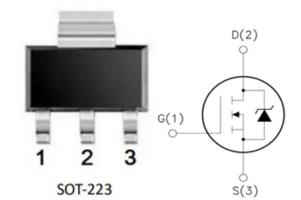
#### **ORDERING INFORMATION**

Package Type	Part Number			
SOT-223	N	AM05N10NR		
SPQ:2,500pcs/Reel	IN	AM05N10NVR		
Note	V: Halogen free Package			
Note	R: Tape & Reel			
AiT provides all RoHS products				

## FEATURE

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

## PIN DESCRIPTION



Pin#	Symbol	Function
1	G	Gate
2	D	Drain
3	S	Source

## ABSOLUTE MAXIMUM RATINGS

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T <sub>A=</sub> 25°C, unless otherwise noted	
V <sub>DS</sub> , Drain-Source Voltage	100V
V <sub>GS</sub> , Gate-Source Voltage	±20V
I <sub>D</sub> , Drain Current Continuous	5A
I <sub>DM</sub> , Drain Current-Pulsed Drain <sup>(1)</sup>	21A
P <sub>D</sub> , Maximum Power Dissipation	5W
T <sub>J</sub> , T <sub>STG</sub> , Operation Junction and Storage Temperature Range	-55°C~+150°C
R <sub>0JA</sub> , Thermal Resistance, Junction-Ambient	41.7°C/W

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## ELECTRICAL CHARACTERISTICS

#### $T_A = 25^{\circ}C$ , unless otherwise noted.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Off Characteristics	÷					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	100	110	-	V
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	-	-	800	nA
Gate-Body Leakage Current	Igss	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	_	±100	nA
On Characteristics <sup>(3)</sup>			•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	1	1.8	3	V
Drain-Source On-State Resistance	RDS (on)	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	-	125	145	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V, I <sub>D</sub> =2.9A	-	8	-	S
Dynamic Characteristics <sup>(4)</sup>	·					
Input Capacitance	Ciss	V <sub>DS</sub> =25V,	-	210	-	
Output Capacitance	Coss	V <sub>GS</sub> =0V,	-	30	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	14	-	
Switching Characteristics <sup>(4)</sup>	·					
Turn-on Delay Time	t <sub>d(ON)</sub>	V <sub>DD</sub> =50V,	-	15	-	
Turn-on Rise Time	tr	$I_{\rm D}=5A,$	-	3.4	-	- 0
Turn-Off Delay Time	td(OFF)	V <sub>GS</sub> =10V, R <sub>G</sub> =2.5Ω,	-	21	-	nS
Turn-Off Fall Time	t <sub>f</sub>	R∟=15Ω	-	3.1	-	
Total Gate Charge	Qg	V <sub>DS</sub> =50V,	-	4.5	-	
Gate-Source Charge	Q <sub>gs</sub>	I <sub>D</sub> =5A,	-	1.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V -		1.2	-	
Drain-Source Diode Characteristics				-		
Diode Forward Voltage <sup>(3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =6A	-	-	1.2	V
Diode Forward Current <sup>(2)</sup>	Is		-	-	5	А

(1) Repetitive Rating: Pulse width limited by maximum junction temperature.

(2) Surface Mounted on FR4 Board,  $t \le 10$  sec.

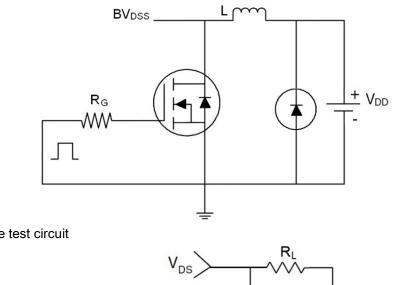
(3) Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

(4) Guaranteed by design, not subject to production

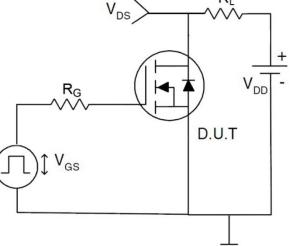


## TEST CIRCUIT

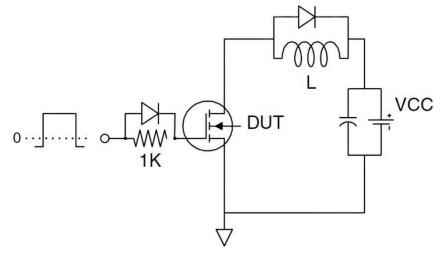
(1) EAS test circuit



(2) Gate charge test circuit



(3) Switch Time Test Circuit





# TYPICAL PERFORMANCE CHARACTERISTICS

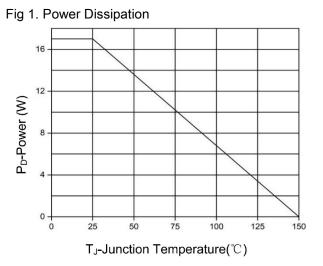
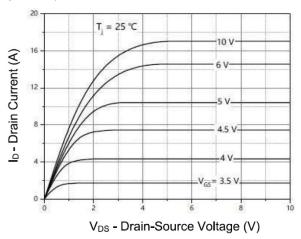
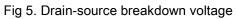


Fig 3. Output characteristics





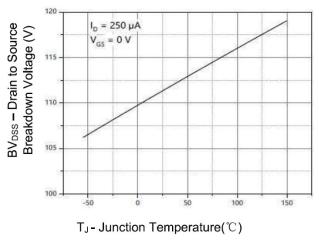


Fig 2. Drain Current

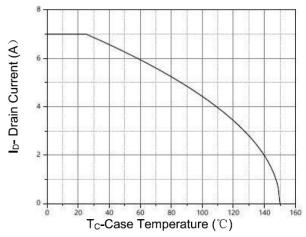
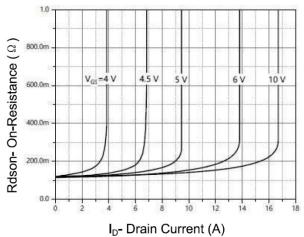
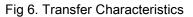
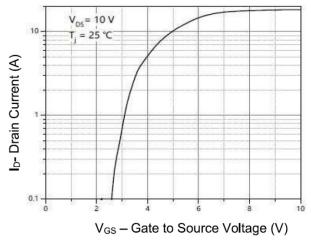


Fig 4. Drain-Source On-state resistance









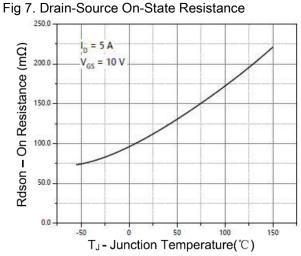
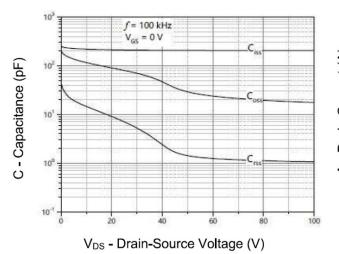
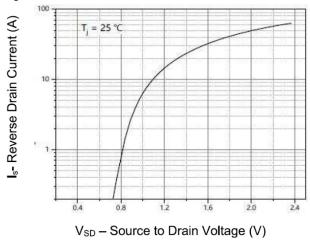


Fig 9. Capacitance vs Vds







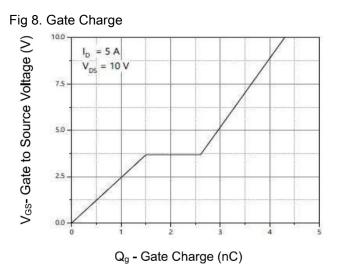
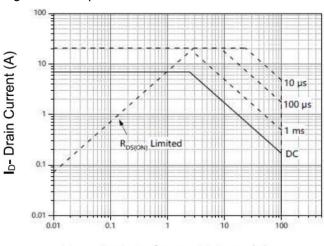


Fig 10. Safe Operation Area

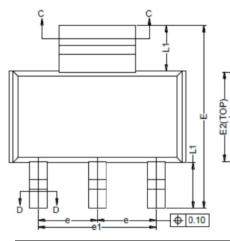


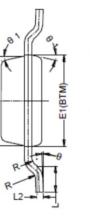


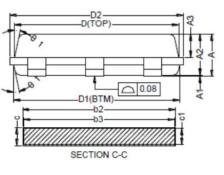


## PACKAGE INFORMATION

Dimension in SOT-223 (Unit: mm)









Symbol	Min.	Max.	Symbol	Min.	Max.
A	-	1.800	E	6.800	7.200
A1	0.020	0.100	E1	3.400	3.600
A2	1.500	1.700	E2	3.330	3.530
A3	0.800	1.000	е	2.300(BSC)	
В	0.670	0.800	e1	4.600(BSC)	
b1	0.660	0.760	L	0.800	1.200
b2	2.960	3.090	L1	1.750(BSC)	
b3	2.950	3.050	L2	0.250(BSC)	
с	0.300	0.350	R	0.100	-
c1	0.290	0.310	R1	0.100	-
D	6.480	6.580	θ	0°	8°
D1	6.550	6.650	θ1	10°	14°
D2	-	7.050			



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